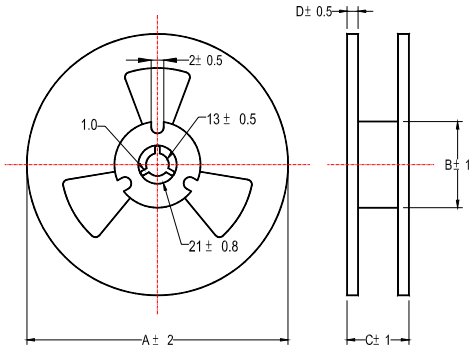
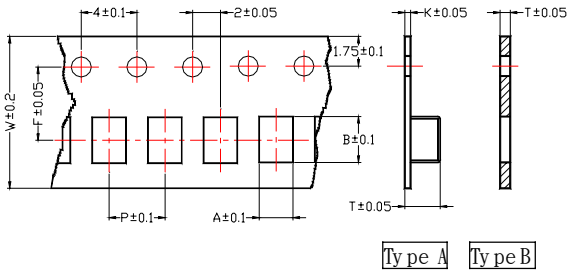
# MULTILAYER FERRITE CHIP BEADS

## Packaging

### Reel Specifications

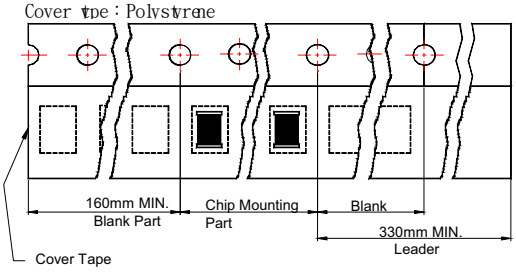



### Tape Specifications

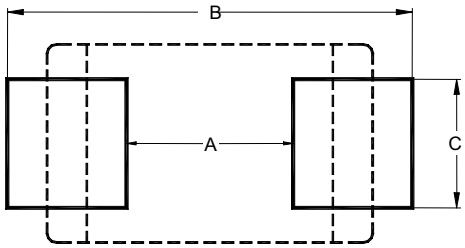



### Tape Material

Carrier tape : Polystyrene for 321609
Cover tape : Polystyrene




### Recommended Patternl




∗ Don't apply narrower pattern than listed above to CB□□YTYH .
Narrow pattern might cause excessive heat or open circuit.

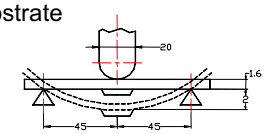
Dimensions in mm

| TYPE | Tape Dimensions | | | | | | | | Reel Dimensions | | | | Recommended Pattern | | | Quantity /Reel |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | A | B | T | W | P | F | K | Tape Typ. | A | B | C | D | A | B | C | |
| CB02 | 0.62 | 1.15 | 0.7 | 8.0 | 2.0 | 3.5 | - | B | 178 | 60 | 10 | 2 | 0.4 | 1.2 ~ 1.4 | 0.4 | 10000 |
| CB03 | 1.05 | 1.80 | 0.95 | 8.0 | 4.0 | 3.5 | - | B | 178 | 60 | 10 | 2 | 0.8 | 2.4 ~ 3.4 | 0.6 | 4000 |
| CB05 | 1.42 | 2.30 | 1.05 | 8.0 | 4.0 | 3.5 | 0.2 | A | 178 | 60 | 10 | 2 | 1.2 | 3.0 ~ 4.0 | 1.0 | 4000 |
| CB04 | 1.88 | 3.50 | 1.27 | 8.0 | 4.0 | 3.5 | 0.2 | A | 178 | 60 | 10 | 2 | 2.0 | 4.2 ~ 5.2 | 1.2 | 3000 |
| CB06 | 1.88 | 3.64 | 1.90 | 8.0 | 4.0 | 3.5 | 0.2 | A | 178 | 60 | 10 | 2 | 2.0 | 4.2 ~ 5.2 | 1.2 | 2000 |
| CB10 | 2.77 | 3.42 | 1.65 | 8.0 | 4.0 | 3.5 | 0.2 | A | 178 | 60 | 10 | 2 | 2.0 | 5.5 ~ 6.5 | 1.8 | 2500 |
| CB08 | 1.88 | 4.95 | 1.90 | 12 | 4.0 | 5.5 | 0.3 | A | 178 | 60 | 14 | 2 | 3.0 | 5.5 ~ 6.5 | 1.2 | 2000 |
| CB12 | 3.66 | 4.95 | 1.85 | 12 | 8.0 | 5.5 | 0.3 | A | 178 | 60 | 14 | 2 | 3.0 | 5.5 ~ 6.5 | 2.4 | 1000 |



RoHS

# Environmental Characteristics

| | Item | Specification | Test Method |
|---|---|---|---|
| 1 | Flexure Strength | Appearance: No damage<br>Z change: within±20%<br>RDC: within specification | Test device shall be soldered on the substrate<br>Substrate Dimension: 100x40x1.6mm<br>Deflection: 2.0mm<br>Keeping Time: 30sec<br>*For 100505, substrate dimension is 100x40x0.8mm<br>  |
| 2 | Vibration | | Test device shall be soldered on the substrate<br>Oscillation Frequency: 10 to 55 to 10Hz for 1min<br>Amplitude: 1.5mm<br>Time: 2hrs for each axis (X, Y & Z), total 6hrs |
| 3 | Resistance to Soldering Heat | Appearance: No damage | Pre-heating: 150℃, 1min<br>Solder Composition: Sn/Pb = 63/37<br>Solder Temperature: 260±5℃<br>Immersion Time: 10±1sec |
| 4 | Solderability | The electrodes shall be at least 90% covered with new solder coating | Pre-heating: 150℃, 1min<br>Solder Composition: Sn/Pb = 63/37<br>Solder Temperature: 230±5℃<br>Immersion Time: 4±1sec |
| | Terminal Strength Test | 100505 series：≧ 0.2 kg<br>160808 series：≧ 0.5 kg<br>201209 series：≧ 1.0 kg<br>other series：≧ 2.0 kg | Test device shall be soldered on the substrate<br>  |
| | Temperature Cycle | Appearance: No damage<br>Z change: within±20%<br>RDC: within specification | One cycle:<br>Step / Temperature (℃) / Time (min)<br>1 / -55±3 / 30<br>2 / 25±2 / 3<br>3 / 125±3 / 30<br>4 / 25±2 / 3<br>Total: 100cycles<br>Measured after exposure in the room condition for 24hrs |
| | Humidity Resistance | | Temperature: 40±2℃<br>Relative Humidity: 90 ~ 95%<br>Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |
| 8 | High Temperature Resistance | | Temperature: 125±3℃<br>Relative Humidity: 0%<br>Applied Current: Rated Current<br>Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |
| 9 | Low Temperature Resistance | | Temperature: -55±3℃<br>Relative Humidity: 0%<br>Time: 1000hrs<br>Measured after exposure in the room condition for 24hrs |